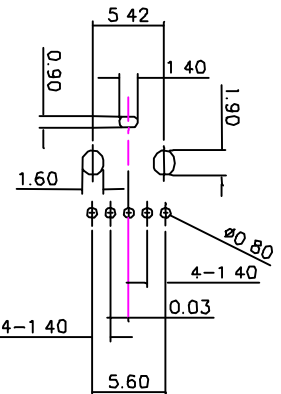
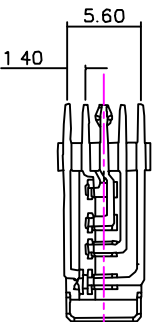
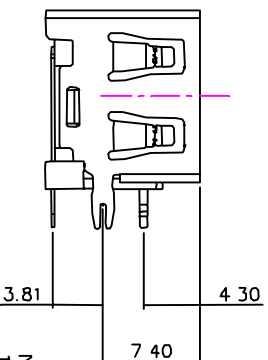
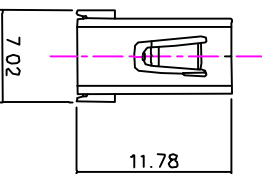
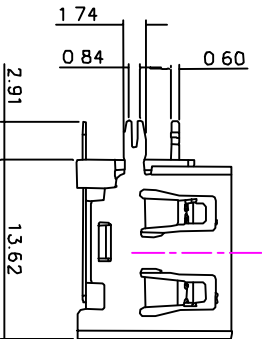
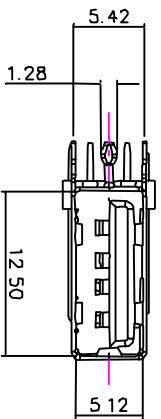


RoHS



RECOMMENDED PCB LAYOUT

MAPX	MODIFICATION	DRW	DATE

NOTE

1. MATERIAL  
HOUSING: THERMOPLASTIC  
SHELL: SPCC OR COPPER ALLOY  
CONTACT: COPPER ALLOY
2. ELECTRICAL PERFORMANCE:
  - 2.1 CURRENT: 2A MIN.
  - 2.2 CONTACT RESISTANCE 30mOHMS MAX.
  - 2.3 DIELECTRIC STRENGTH  
UNMATED: 500V AC RMS
  - 2.4 INSULATION RESISTANCE: 100MOMHS MIN
3. MECHANICAL PERFORMANCE:
  - 3.1 INSERTION FORCE: 35N MAX.
  - 3.2 WITHDRAWAL FORCE: 4N MIN.  
35N MAX.
  - 3.3 TEMPERATURE RANGE: -25°C TO 85°C

产品图  
PRODUCT CHART DWG

公差一览表 TOLERANCE UNLESS OTHERWISE	
X	±0.35
X	±0.20
XX	±0.10
XXX	±0.05
X	±5°
X	±2°
XX	±1°
XXX	±0.5°

深圳市精拓金电子有限公司  
Shenzhen Jing Tuo Jin Electronics Co., Ltd.

单位	MM	制图	许榕强	制图料号	
比例	1:1	审核	郭治富	产品名称	USB AF 微USBPIN
日期	2016-09-09	核准	黄国荣	产品 No.	

XXX	±0.05	XXX	±0.5°
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G 1 2 3 4 5 6 7 8 9 10  
F  
E  
D  
C  
B  
A